

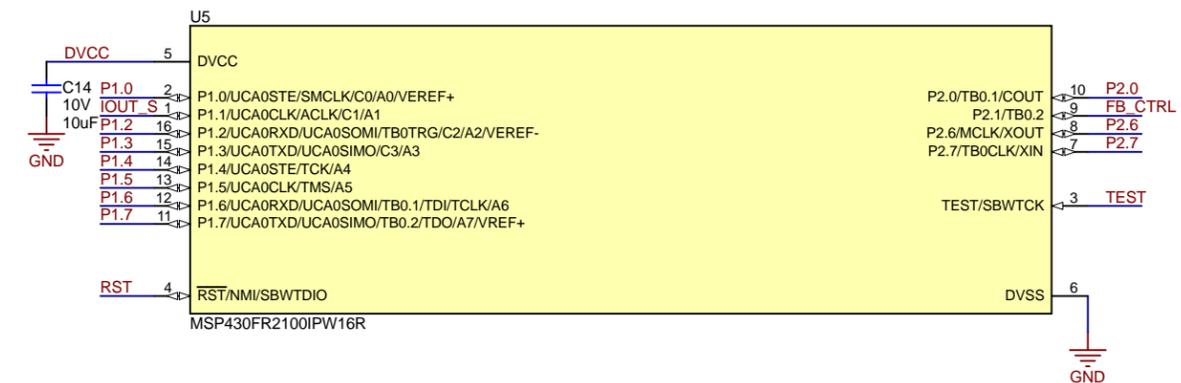
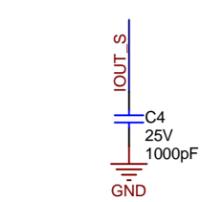
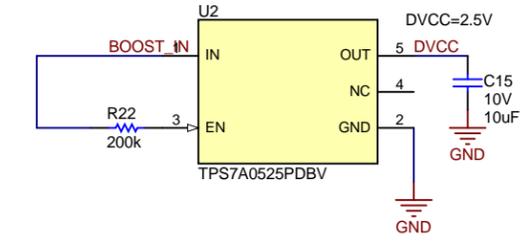
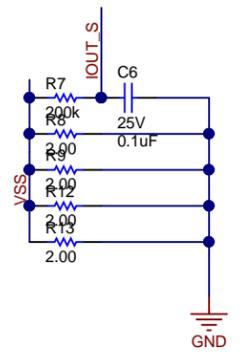
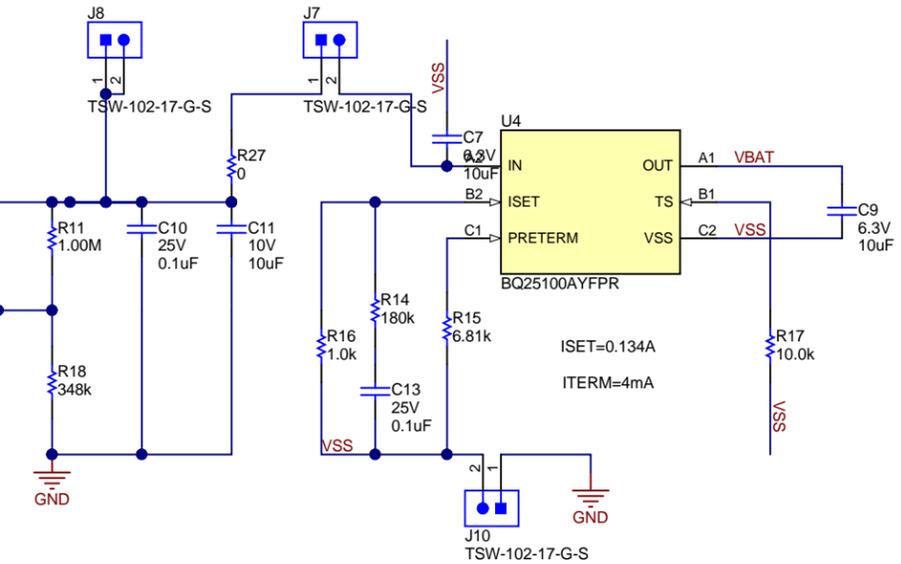
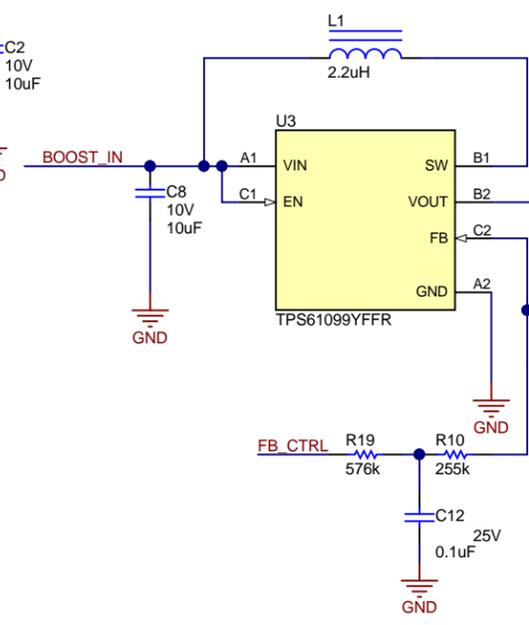
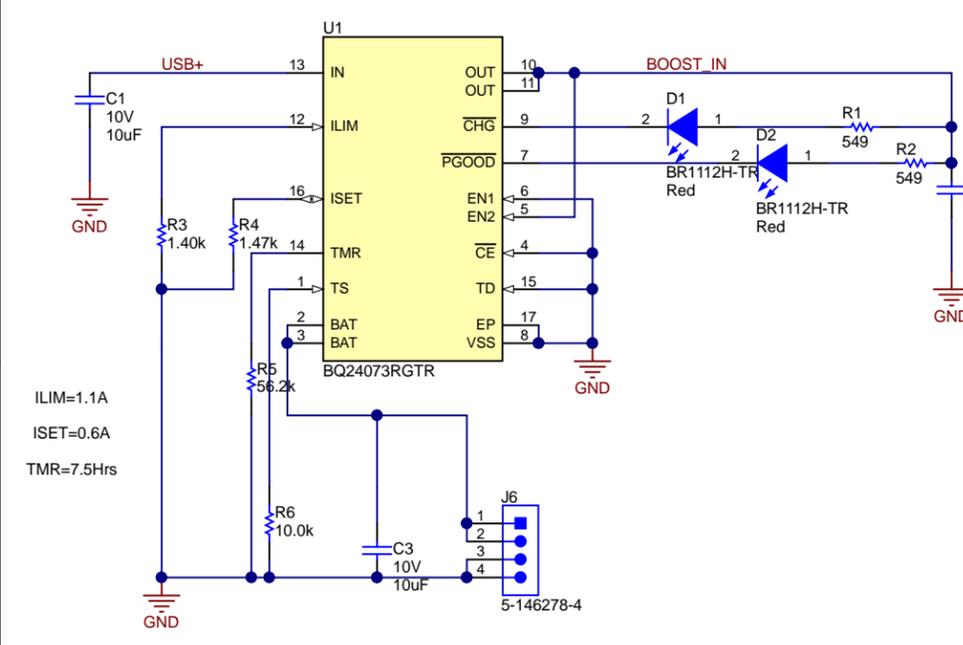
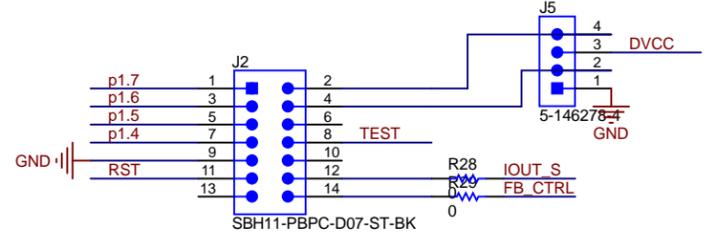
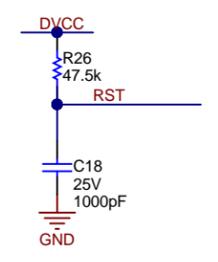
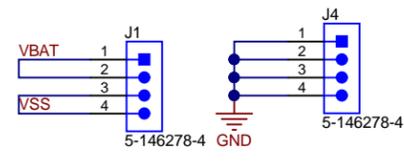
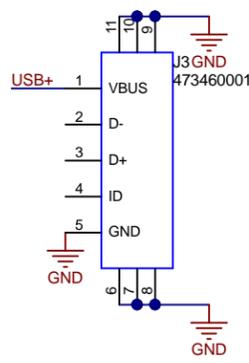
Revision History

Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A

Place Block Diagram here (if appropriate) or delete this text box.
 If using a block diagram from another tool, save the picture as a .bmp file.
 Then, use menu Place|Drawing Tools|Graphic to insert the .png/.svg/.bmp file on the schematic.

Orderable: ChangeMe in variant	Designed for: Public Release	Mod. Date: 5/28/2017	 TEXAS INSTRUMENTS http://www.ti.com © Texas Instruments 2018
TID #: TIDA-050007	Project Title: Ultra-low Power Reference Design for Wireless Earbuds		
Number: TIDA-050007 Rev: E1	Sheet Title:		
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3	
Drawn By:	File: charging case_CoverSheet_SchDoc	Size: B	
Engineer: Charles Wong	Contact: http://www.ti.com/support		

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TID #: TIDA-050007	Project Title: Ultra-low Power Reference Design for Wireless Earbuds		
Number: TIDA-050007 Rev: E1	Sheet Title:		
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3	
Drawn By:	File: charging case BlankSheet.SchDoc	Size: B	
Engineer: Charles Wong	Contact: http://www.ti.com/support		

A

A

PCB Number: TIDA-050007
PCB Rev: E1

PCB
LOGO
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PCB
LOGO
WEEE logo

You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You should delete this note too.

B

B

Variant/Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
THT-14-423-10
Size: 0.65" x 0.20 "

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

C

C

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

D

D

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TID #: TIDA-050007	Project Title: Ultra-low Power Reference Design for Wireless Earbuds		
Number: TIDA-050007 Rev: E1	Sheet Title:		
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3	
Drawn By:	File: charging case EVM Hardware.SchDoc	Size: B	
Engineer: Charles Wong	Contact: http://www.ti.com/support		

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